



Physical Interfaces & Carriers Global Technical Committee

Japan TC Chapter Meeting

Japan Standards Winter Meetings 2025
Thursday, December 18, 2025
TFT Building, Tokyo, Japan in conjunction with SEMICON Japan 2025
/ Official Virtual TC Chapter Meeting [Hybrid]
9:00am - 12:00pm JST

AGENDA

1. **Welcome / Call to Order**
 - 1.1 Introductions
 - 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
 - 1.3 Agenda Review
2. **SEMI Japan Technical Committee Award Ceremony**
3. **Review of Previous Meeting Minutes**
4. **Liaison Report**
 - 4.1 North America
 - 4.2 JRSC
5. **Staff Report**
6. **Ballot Review**

#	When	TF	Details
7373A	Cycle 9, 2025	Panel Level Packaging (PLP) Panel FOUP Task Force	Line Item Revision to SEMI E182-0925 - Specification for Panel FOUP Loadport for Panel Level Packaging
7402	Cycle 9, 2025	Panel Level Packaging (PLP) Panel FOUP Task Force	Line Item Revision to SEMI E181.1 — Specification for Panel FOUP for 510 to 515 mm Panel Size and 12 Slots, SEMI E181.2 — Specification for Panel FOUP for 510 to 515 mm Panel Size and 6 Slots, SEMI E181.3 — Specification for Panel FOUP for 600 to 600 mm Panel Size and 12 Slots and SEMI E181.4 — Specification for Panel FOUP for 600 to 600 mm Panel Size and 6 Slots

7. **Preliminary Standard**
 - 7.1 Doc. 7375, New Preliminary Standard: Specification for Large Tray Stack FOUP (LTSF): GCS Approval Result
 - 7.2 New Preliminary Standard: Specification for Enhanced Handoff Interface: SNARF Approval (New Business)
8. **Subcommittee & Task Force Reports**
 - 8.1 Global PIC Standards Maintenance TF
 - 8.2 Japan Electron Microscopy Workflow liaison TF
 - 8.3 Panel Level Packaging Panel FOUP TF
 - 8.4 Next Gen Assembly / Test Material Handling TF
 - 8.5 310mm Square Panel FOUP Task Force

- 8.6 [Liaison: 3D Packaging & Integration JA TCC] Panel Level Packaging Glass Carrier TF
- 8.7 [Liaison: 3D Packaging & Integration NA TCC] Panel Level Packaging Panel TF

9. Old Business

- 9.1 Project Period Review
- 9.2 5 Year Review

10. New Business

- 10.1 SNARF Approval
 - 10.1.1 New Preliminary Standard: Specification for Enhanced Handoff Interface

11. Action Item Review

11.1 Open Action Items

#	Assigned to	Details
PIC_20250926_1	SEMI Staff	Distribution the two SNARFs to TC members. (NGAT TF)
PIC_20250926_2	SEMI Staff	Preliminary Standards: GCS Approval
PIC_20250926_3	Shoji Komatsu	Submission updated TFOF and SNARF about 310mm square Panel FOUP TF

11.2 New Action Items

#	Assigned to	Details

12. Next Meeting and Adjournment